

Title (en)  
Lead-free copper alloy and use thereof

Title (de)  
Bleifreie Kupferlegierung und deren Verwendung

Title (fr)  
Alliage de cuivre sans plomb et son utilisation

Publication  
**EP 1452613 B1 20071205 (DE)**

Application  
**EP 04002009 A 20040130**

Priority  
DE 10308778 A 20030228

Abstract (en)  
[origin: EP1452613A2] The Cu-Zn-Si based alloy comprises in wt%: Cu 70-83, Si 1-5. The following matrix-active elements are also included: Sn 0.01-2, Fe and/or Co 0.01-3, Ni 0.01-0.3, Mn 0.01-0.3, P up to 0.1 (optional), and up to 0.5% of Ag, Al, As, Mg, Sb, Ti, Zr. The remainder is Zn, with inevitable impurities.

IPC 8 full level  
**C22C 9/10** (2006.01); **C22C 9/04** (2006.01)

CPC (source: EP US)  
**C22C 9/04** (2013.01 - EP US); **C22C 9/10** (2013.01 - EP US)

Cited by  
EP1936388A1; CN104018047A; WO2012104426A2; WO2023138974A1

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AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)  
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**EP 04002009 A 20040130**; AT 04002009 T 20040130; AU 2004200784 A 20040227; CA 2458723 A 20040225; CN 200410004293 A 20040218; DE 10308778 A 20030228; DE 502004005634 T 20040130; DK 04002009 T 20040130; JP 2004041154 A 20040218; US 78803704 A 20040226